

S/N 10/623,788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Leonard Forbes et al.	Examiner:	Pamela Perkins
Serial No.:	10/623,788	Group Art Unit:	2822
Filed:	July 21, 2003	Docket:	1303.109US1
Customer No.:	73115	Confirmation No.:	6087
Title:	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Applicant brings to the attention of the Examiner the following Office Actions and responses associated with one or both of the inventors of the instant application and/or the assignee of the instant application. This material is available and accessible at the United States Patent and Trademark Office.

STRAINED SEMICONDUCTOR BY WAFER BONDING WITH MISORIENTATION

Application Serial No.11/318,124 (Atty Ref 1303.095US3), Notice of Allowance mailed 01/11/2008, 11 pgs

MICROMECHANICAL STRAINED SEMICONDUCTOR BY WAFER BONDING

Application Serial No.11/432,578 (Atty Ref 1303.100US3), Non-Final Office Action mailed 01/11/2008, 12 pgs

MICRO-MECHANICALLY STRAINED SEMICONDUCTOR FILM

Application Serial No. 11/707,214 (Atty Ref 1303.089US3) Response filed 1-14-08 to Non Final Office Action mailed 10-12-07, 7 pgs
Application Serial No. 11/707,214 (Atty Ref 1303.089US3) Notice of Allowance mailed 03-28-2008, 12 pgs

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications, and Non-Published Applications identifiable by USPTO Serial Number, are no longer required to be provided to the Office. Notification of this change to this effect was provided in the United States Patent and Trademark Office OG Notice dated October 19, 2004. Thus, Applicant has not included copies of any US Patents or US Patent Applications identifiable by serial number that may be cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).


The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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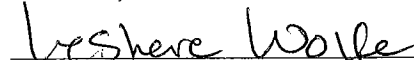
Date 5-13-08

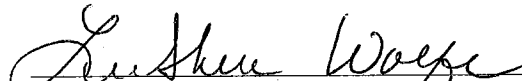
By



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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 13th day of May, 2008.


Name


Signature